



DATA SHEET

CHIP Low Leakage Current

Serie: I15004

Voltage: 25Volt

Range: 33 μ F

Impedance: 9,1 Ω

Dimension 6,3x5,4mm

Ripple Current: 63mA

CHIP Low Leakage Current

Serie No.: **I15004**

| | | | | | | | | | | |
|-------|--------|------|--------|--------|--------|-----------|-----------|----------|------------|-----------|
| DRW: | Jason | CHKD | Wilson | MATL: | Wilson | TOLERANCE | Mason | DATE | 03.06.2014 | Customer: |
| APPD: | Schumi | | | FINISH | Jamy | | Sheet No. | 1 from 7 | | |

EDCON-COMPONENTS



Designed for surface mounting on high density circuit board

Emboss carrier tape packing systems is available for automatic insertion



Technical Informations

| | |
|--|------------------|
| Voltage: | 25Volt |
| Range; | 33μF |
| Dimension; D x L mm | 6,3x5,4mm |
| Impedance (Ω) max., at20°C, 100hKz | 9,1Ω |
| Ripple Current (mA rms) at 105°C, 100kHz | 63mA |

| Ordering Code | | | |
|---------------|----------------|-----------|----------|
| 250 | Voltage | | |
| 330 | Range | | |
| D= | C | L= | 0 |

- Low Leakgae current (0,5μA to 3,3μA max).
- Low cost for replacement of some tantalum applications
- Low Impedance with Operating Temperatur Range of -40°C ~ +85°C
- Load Life of 2000hours

| | |
|-----------------------------|--|
| Leakage current max. | I = 0,002CV or 0,5μA whichever is greater (after 2 minutes) |
|-----------------------------|--|

| | | | | | | | | | | | | |
|---|----------------------|-------------|------|------|------|------|------|------|--|--|--|--|
| Capacitance tolerance | ± 20% at 120Hz, 20°C | | | | | | | | | | | |
| Dissipation factor max. (at 120Hz, 20°C) | | WV | | | | | | | | | | |
| | Tanδ | Ø4 ~ Ø6,3mm | 6,3 | 10 | 16 | 25 | 35 | 50 | | | | |
| | | | 0,24 | 0,20 | 0,16 | 0,14 | 0,12 | 0,10 | | | | |

| | | | | | | | | | | | | |
|--|--|-----------------|-----|----|----|----|----|----|--|--|--|--|
| Low Temperatur characteristics (Impedance ratio at 120Hz) | | WV | | | | | | | | | | |
| | | Z-25°C / Z+20°C | 6,3 | 10 | 16 | 25 | 35 | 50 | | | | |
| | | Z-40°C / Z+20°C | 4 | 3 | 2 | 2 | 2 | 2 | | | | |
| | | | 8 | 6 | 4 | 4 | 3 | 3 | | | | |

| | | |
|---|--------------------------|-----------------------------------|
| Load Life (after application of the rated voltage for 2000hrs at 85°C | Leakage current | Less than specified value |
| | Capacitance Change | Within ±25% of initial value |
| | Tanδ | Less than 200% of specified value |
| | Ø4 ~ Ø6,3x5,4: 1000hours | |

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| | | |
|-------------------------------------|---|------------------------------------|
| Resistance to soldering heat | After reflow soldering and resistance at room temperature, they meet the characteristics requirements listed at underside | |
| | Leakage current | Less than specified value |
| | Capacitance Change | Within $\pm 10\%$ of initial value |
| | Tan δ | Less than specified value |

| FREQUENCY COEFFICIENT OF PERMISSIBLE RIPPLE CURRENT | | | | | | |
|---|------|-------|-------|------|--------------|--|
| Frequency | 50Hz | 120Hz | 300Hz | 1KHz | 10KHz \leq | |
| Coefficient | 0,70 | 1,00 | 1,17 | 1,36 | 1,50 | |

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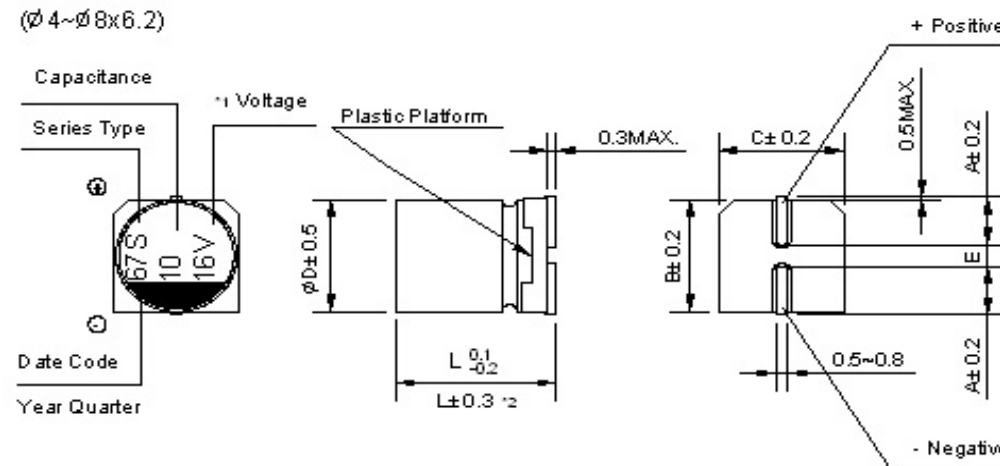


Technical Drawing

Dimension of Size Ø 8x10,5 ~ 16mm



Dimension of Size Ø 4~ 8x6,2mm



| D x L | Ø 4 x 5.4 | Ø 5 x 5.4 | Ø 6,3 x 5.4 | Ø 6,3 x 7,7 | | | | | | |
|----------|-----------|-----------|-------------|-------------|--|--|--|--|--|--|
| A | 2,0 | 2,2 | 2,6 | 2,6 | | | | | | |
| B | 4,3 | 5,3 | 6,6 | 6,6 | | | | | | |
| C | 4,3 | 5,3 | 6,6 | 6,6 | | | | | | |
| E +/-0.2 | 1,0 | 1,3 | 1,9 | 1,9 | | | | | | |
| L | 5,4 | 5,4 | 5,4 | 7,7 | | | | | | |

*1 Voltage mark (6V) represents 6,3V for Ø 4 ~ 10mm

*3 (L +/- 0.5) is applicable to Ø 8x10,5 ~ Ø 10mm

*2 (L +/- 0.3) is applicable to Ø 6,3 ~ 7.7 and Ø 8 + 6,2mm

*4 (L +/- 1.0) is applicable to Ø 12,5 ~ Ø 16mm

RE. Date code and seriew type -1st digit for Year 2nd digit for Quarter, 4 quarter codes in one year area 1,4,7,0

3rd character for Serie S

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| Voltage Ordering Code | Code |
|-----------------------|------------|
| 4,0 | 4V0 |
| 6,3 | 6V3 |
| 10 | 100 |
| 16 | 160 |
| 25 | 250 |
| 35 | 350 |
| 50 | 500 |
| 63 | 630 |
| 80 | 800 |
| 100 | 101 |
| | |
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| | |

| Diameter ordering Code D | Code |
|--------------------------|----------|
| 3mm | 3 |
| 4mm | A |
| 5mm | B |
| 6,3mm | C |
| 8mm | E |
| 10mm | G |
| 12,5mm | I |
| 16mm | K |

| Height ordering Code L | Code |
|------------------------|----------|
| 4mm | A |
| 5,4mm | 0 |
| 5,8mm | 1 |
| 6,2mm | 2 |
| 7,7mm | 3 |
| 10,5mm | 4 |
| 13,5mm | 5 |
| 16mm | 6 |
| 16,5mm | 7 |

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Ordering Informations

| Serie | Voltage Code | Tolerance Code | Range Code | Size Code D | Size Code L | Special function | ROHS | Packing Code | | |
|-------|--------------|----------------|------------|-------------|-------------|------------------|------|--------------|--|--|
|-------|--------------|----------------|------------|-------------|-------------|------------------|------|--------------|--|--|

| | | | | | | | | | | |
|---------------|------------|----------|------------|----------|----------|-----------|----------|-----------|--|--|
| I15004 | 250 | M | 330 | C | 0 | XX | R | TR | | |
|---------------|------------|----------|------------|----------|----------|-----------|----------|-----------|--|--|

| | | | | | | | | | |
|-------------------------|----------------|---------------------|-------------------|-------------------|------------------------|--|--|--|--|
| look table Voltage Code | M= ±20% | Ordering Code Range | Look table Code D | Look table Code L | XX= No function | R= ROHS Conform N= NON ROHS Conform | TR= Tape Reel Packing BU= Bulk-Ware | | |
|-------------------------|----------------|---------------------|-------------------|-------------------|------------------------|--|--|--|--|

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Soldering Profile Curve

Classification Reflow Profile (JEDEC J-STD-020C)



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